

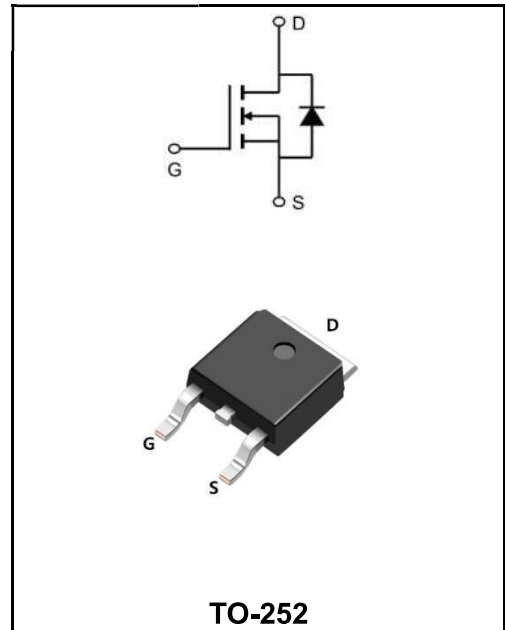
**1000V N-CHANNEL ENHANCEMENT MODE MOSFET**

**MAIN CHARACTERISTICS**

<b>I<sub>D</sub></b>	2A
<b>V<sub>DSS</sub></b>	1000V
<b>R<sub>DS(on)-typ</sub>(@V<sub>GS</sub>=10V)</b>	< 7.2Ω (Type:6Ω)

**Application**

- ◆Uninterruptible Power Supply(UPS)
- ◆Power Factor Correction (PFC)



**Product Specification Classification**

Part Number	Package	Marking	Pack
YFW2N100AD	TO-252	YFW 2N100AD XXXXX	2500PCS/Tape

**Maximum Ratings at T<sub>c</sub>=25°C unless otherwise specified**

Characteristics	Symbols	Value	Units
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DS</sub>	1000	V
Continuous Drain Current	I <sub>D</sub>	2	A
Pulsed Drain Current	I <sub>DM</sub>	8	A
Gate - Source Voltage	V <sub>GS</sub>	±30	V
Single Pulse Avalanche Energy	E <sub>AS</sub>	45	mJ
Avalanche Current	I <sub>AR</sub>	3	A
Repetitive Avalanche Energy	E <sub>AR</sub>	27	mJ
Power Dissipation(T <sub>c</sub> =25°C)	P <sub>D</sub>	75	W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C
Thermal Resistance, Junction-to-case	R <sub>θJC</sub>	1.67	K/W
Thermal Resistance, Junction ambient	R <sub>θJA</sub>	60	K/W

**Maximum Ratings at Tc=25°C unless otherwise specified**

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	<b>V(BR)DSS</b>	1000	-	-	<b>V</b>
Zero Gate Voltage Drain Current	$V_{DS}=1000V, V_{GS}=0V, T_J=25^\circ C$	<b>I<sub>DSS</sub></b>	-	-	1	<b>μA</b>
Gate-Source Leakage	$V_{GS}=\pm 20V$	<b>I<sub>GSS</sub></b>	-	-	±100	<b>nA</b>
Gate- Source Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	<b>V<sub>GS(th)</sub></b>	2.0	-	4.0	<b>V</b>
Drain-Source On-Resistance (note3)	$V_{GS}=10V, I_D=1A$	<b>R<sub>DS(ON)</sub></b>	-	6	7.2	<b>Ω</b>
Input Capacitance	$V_{DS}=25V$ $V_{GS}=0V$ $f=1MHz$	<b>C<sub>iss</sub></b>	-	419	-	<b>pF</b>
Output Capacitance		<b>C<sub>oss</sub></b>	-	45	-	
Reverse Transfer Capacitance		<b>C<sub>rss</sub></b>	-	9	-	
Total Gate Charge	$V_{DD}=800V$ $I_D=2A$ $V_{GS}=15V$	<b>Q<sub>g</sub></b>	-	16	-	<b>nC</b>
Gate-Source Charge		<b>Q<sub>gs</sub></b>	-	2	-	
Gate-Drain Charge		<b>Q<sub>gd</sub></b>	-	8	-	
Turn-on delay time	$V_{DD}=500V$ $I_D=2A$ $R_G=25\Omega$	<b>t<sub>d(on)</sub></b>	-	36	-	<b>nS</b>
Turn-on Rise Time		<b>T<sub>r</sub></b>	-	12	-	
Turn-Off Delay Time		<b>t<sub>d(OFF)</sub></b>	-	100	-	
Turn-Off Fall Time		<b>t<sub>f</sub></b>	-	43	-	
Continuous Body Diode Current	$T_C=25^\circ C$	<b>I<sub>S</sub></b>	-	-	2	<b>A</b>
Pulsed Diode Forward Current		<b>I<sub>SM</sub></b>	-	-	8	
Body Diode Voltage	$T_J = 25^\circ C, I_{SD} = 1A, V_{GS} = 0V$	<b>V<sub>SD</sub></b>	-	-	1.4	<b>V</b>
Reverse Recovery Time	$V_{GS} = 0V, I_S = 2A$ $diF/dt = 100A/\mu s$	<b>t<sub>rr</sub></b>	-	432.5	-	<b>nS</b>
Reverse Recovery Charge		<b>Q<sub>rr</sub></b>	-	424	-	<b>uC</b>

**Notes**

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. L = 10.0mH, VDD = 50V, RG = 25 Ω, Starting TJ = 25 °C
3. Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 1%

Ratings and Characteristic Curves

Figure 1. Output Characteristics ( $T_J = 25^\circ\text{C}$ )

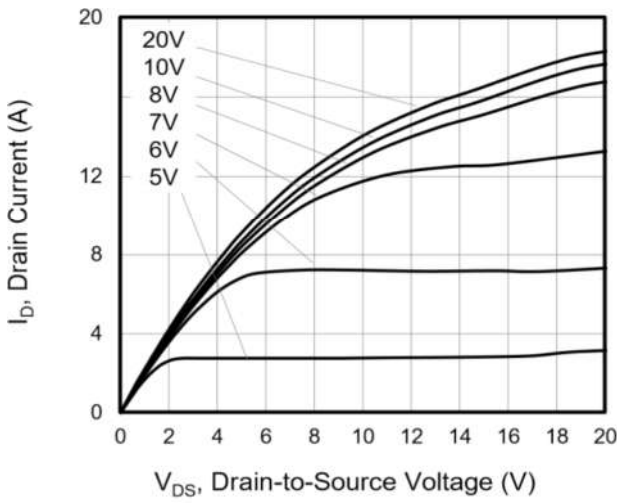


Figure 2. Body Diode Forward Voltage

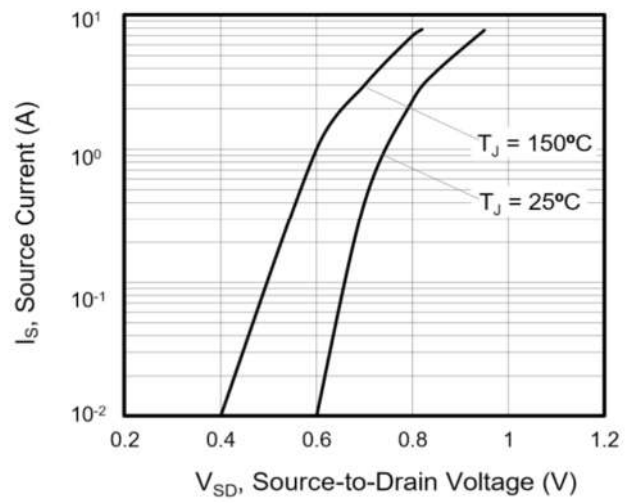


Figure 3. Drain Current vs. Temperature

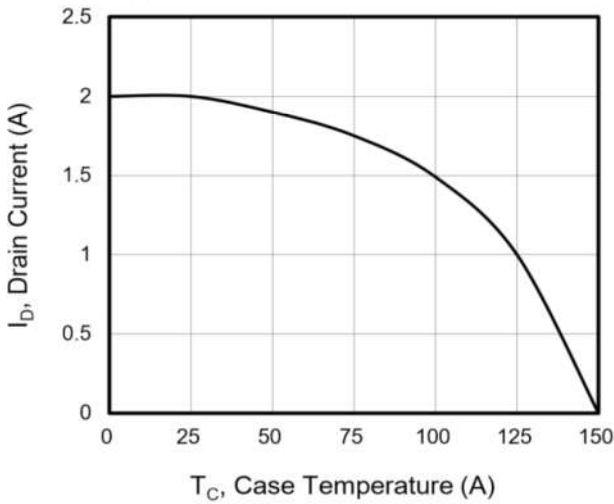


Figure 4.  $BV_{DSS}$  Variation vs. Temperature

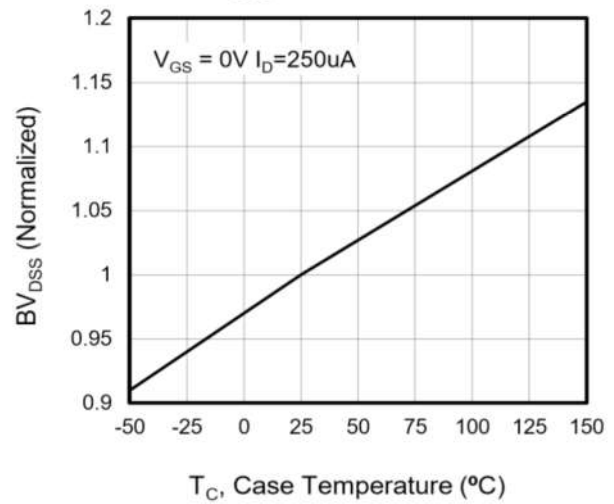


Figure 5. Transfer Characteristics

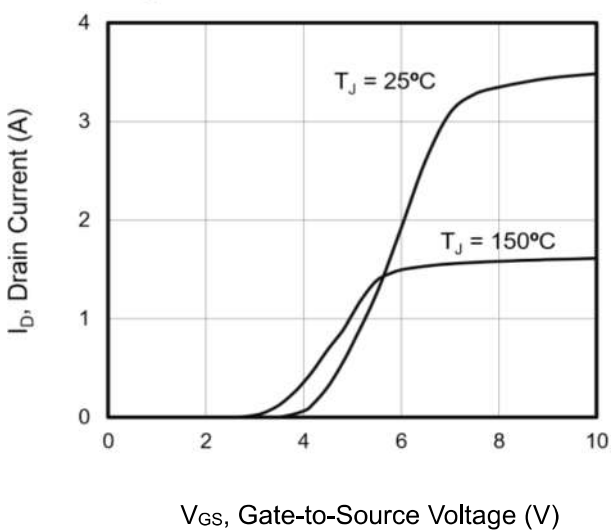
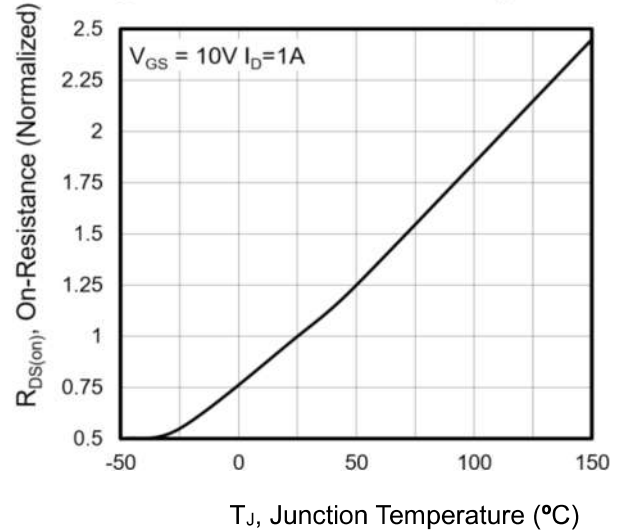
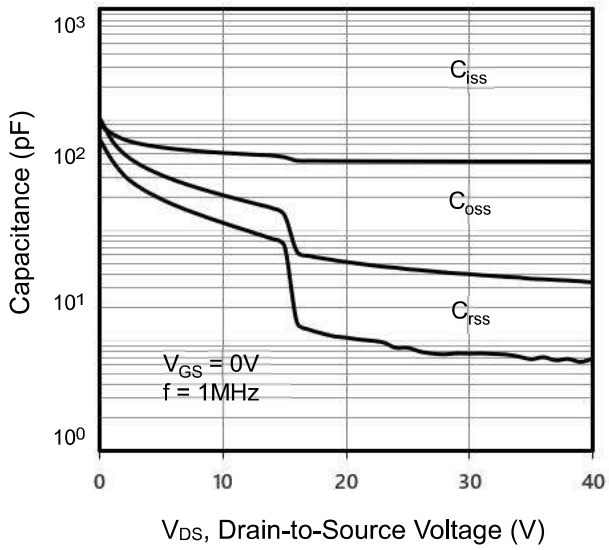


Figure 6. On-Resistance vs. Temperature

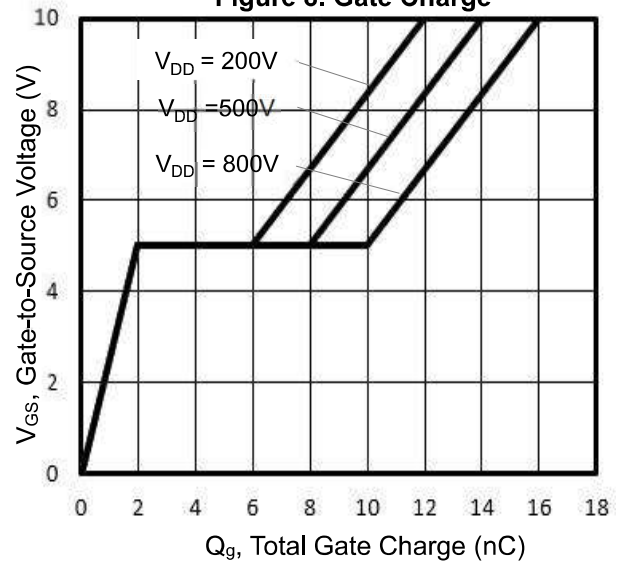


**Ratings and Characteristic Curves**

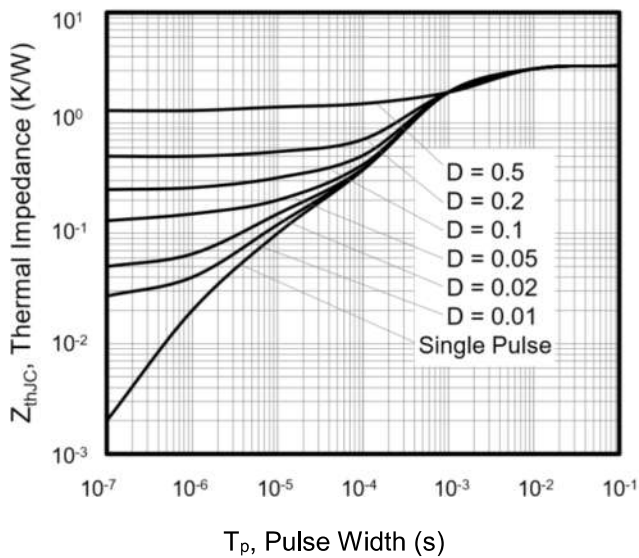
**Figure 7. Capacitance**



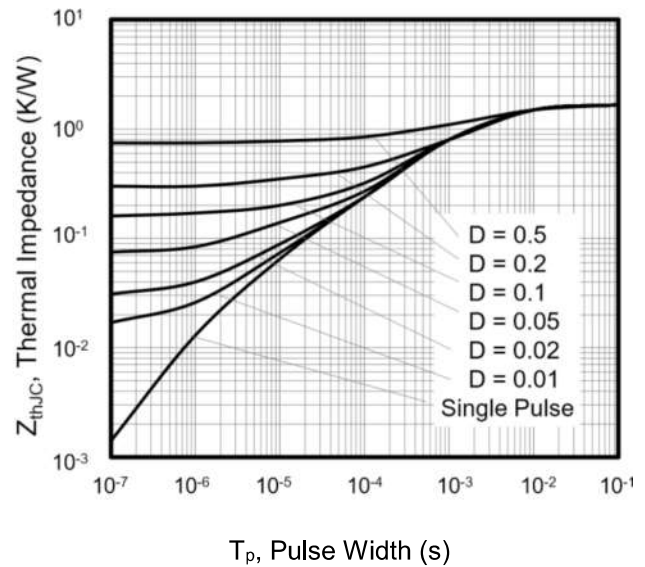
**Figure 8. Gate Charge**



**Figure 9. Transient Thermal Impedance**



**Figure 10. Transient Thermal Impedance**



Package Outline Dimensions Millimeters

TO-252

Dim.	Min.	Typ.	Max.
A	2.10	-	2.50
A2	0	-	0.10
B	0.66	-	0.86
B2	5.18	-	5.48
C	0.40	-	0.60
C2	0.44	-	0.58
D	5.90	-	6.30
D1	5.30REF		
E	6.40	-	6.80
E1	4.63	-	-
G	4.47	-	4.67
H	9.50	-	10.70
L	1.09	-	1.21
L2	1.35	-	1.65
V1	-	7°	-
V2	0°	-	6°
All Dimensions in millimeter			